

09/300,544

Patent

C2
4. (twice amended) The adhesive composition of claim 1 wherein said tackifying resin has a softening point of greater than about 135 [140]°C.

Sh E4
C3
20. (twice amended) A[n improved] hot melt adhesive composition[,] comprising:
a) about 10% by weight to about 50% by weight of at least one tackifying resin having a glass transition temperature of at least 65°C;
b) about 20% to about 60% by weight of at least one thermoplastic polymer selected from the group consisting of copolymers and terpolymers of ethylene; amorphous polyalphaolefins, homogeneous ethylene/α-olefin interpolymer and mixtures thereof; and
c) 0% by weight to about 40% by weight of at least one wax;
wherein said total tackifying resin concentration having a glass transition temperature of greater than 65 °C is less than said total polymer concentration.

Sh E7
C4
30. (amended) A hot melt adhesive composition comprising:
a) about 10% by weight to about 50% by weight of at least one substantially aliphatic tackifying resin having a softening point of greater than 140°C;
b) about 20% to about 60% by weight of at least one thermoplastic polymer; and
c) 0% by weight to about 40% by weight of at least one wax;
wherein said total tackifying resin concentration having a softening temperature of greater than 140 °C is less than said total polymer concentration.

REMARKS

Claims 1, 20 and 30 are amended. Support for the amendments can be found in the claims as filed. No new matter is added.

Claims 1-30 are rejected under 35 U.S.C. § 102 (b) as being anticipated by, or, in the alternative, under 35 U.S.C. § 103 (a) as obvious over Alper. Applicants respectfully traverse the rejection.

A. § 102(b) Rejection

As discussed in the previous response, Alper et al. is directed to hot melt